

## PRELIMINARY AGENDA

### MEETING NUMBER 33

#### CE-2.0 COMMITTEE ON CONNECTOR STANDARDS

October 8, 2003  
San Antonio Marriott River Center  
101 Bowie Street  
San Antonio, TX 78205  
1-800-648-4462

The CE-2.0 Committee on Connector Standards and its Subcommittees, Working Groups, and Special Task Groups will meet on October 8<sup>th</sup>. The meeting will start at 8:00 a.m. and conclude at 4:00 p.m. This meeting will be in conjunction with the ECA Fall Engineering Summit, and the CE-3.0 Committee on Socket Standards. The CE-3.0 meeting will be on October 9<sup>th</sup> beginning at 8:00 a.m.; all CE-2.0 members are invited to participate. The ECA Fall Engineering Summit includes other meetings and speakers directly affecting your business. ( The U-1 committee covers user concerns and new product technology. Issues such as the China CCC approval and how it affects you. Additionally, the Environmental Materials reporting requirements being imposed upon all manufacturers. The Soldering Technology Committee (STC) is dealing with lead-free soldering issues. The Automated Component Handling Committee (ACH) is addressing a new carrier tray standard for miniature connectors and revising the Tape and Reel standard covering component orientation. Visit the ECA website [www.ec-central.org](http://www.ec-central.org) to register, even if it is only for the CE-2.0 meeting. Hotel room reservation cutoff date is 16 September 2003.

**Note: The meeting will run sequentially, with no specific time scheduled for the individual agenda items shown below. The Chairman may vary the sequence as needed. Members are requested to plan on attending the meeting for its full duration (early departures effect the completion of agenda work).**

#### **CE-2.0 AGENDA**

- I. Review and approval of previous meeting minutes. (San Diego: 5/12/03)
- II. Chairman's Report and Announcements
  - A. SUBCOMMITTEE MEETINGS
    - CE-2.2: Circular Connector Specifications (Chairman: Al Davis)
    - CE-2.3: Rectangular Connector Specifications (Chairman: Open)

CE-2.4: Printed Board Connector Specifications (Chairman: Rick Taylor)

STG-22-2.4 High Density Blade & Tuning Fork (Chairman: TBD)  
PN-4090 (Frank Ruffino)

CE-2.5: Backplane Specifications (Chairman: Al Davis)  
(Note: This committee is currently inactive)

CE-2.6: Contact Specifications (Chairman: Dave Bouzek)  
PN on Compliant Pin Guidance Document (Chairman: Max Peel)

CE-2.7: Editing Subcommittee (Chairman: Open)

CE-2.8: International Standards Subcommittee (Chairman: Jeff Toran)

WG-2.8.1 IEC Technical Advisory Group-TC 48 (Chairman: Jeff  
Toran)

#### B. WORKING GROUP (CE-2.0) MEETINGS

- CE-2.0.1: Contact and Connector Plating (Chairman: Bill Upstone)
- CE-2.0.3: Insulator Materials (Chairman: Frank Ruffino)
- CE-2.0.4: Connector Outlines & Surface Mount Activities (Chairman: TBD)

#### C. SPECIAL TASK GROUP (CE-2.0) MEETINGS

- STG-13-2.0: Terminology (Chairman: Open)
- STG-20-2.0: Space Requirements (Chairman: Charles Gamble, Jr.)
- STG-23-2.0: Current vs. Temp. Rise (Chairman: Max Peel)

#### III. CE-2.1 SUBCOMMITTEE ON TEST PROCEDURES (Chairman: Bill Peverill; ViceChairman: Max Peel)

- STG-33-2.1: Electronic Signal Methods (Chairman: Jeff Toran)
- STG-29-2.1: Performance Criteria (Co-Chairmen: John Healey & Max Peel)

#### IV. LIAISON REPORTS

- D. DSCC (Including Army, USAF, Navy [except NAVAIR]) – Rick Taylor
  - E. NAVAIR – Dwight Tabit
  - F. SAE – Dave Bouzek
  - G. ISO – Dave Bouzek
  - H. ASTM – Frank Ruffino
  - I. EIA CE-3.0 – Harvey Waltersdorf
  - J. NASA – Charles Gamble, Jr.
  - K. IICIT – Marty Freedman
- V. Old Business
- Review of Generic Document (EIA-7000000)
- VI. New Business
- Cables & Connectivity Industry Summit: The Executive Forum at the International Wire and Cable Symposium. November 17-18, 2003 Philadelphia Marriott, Philadelphia, PA. For details visit the ECA Website at [www.ec-central.org](http://www.ec-central.org)
  - Committee P-4 Mechanical Outlines Report
  - Strategic Planning Session
- VI. Next Meeting
- Tentative meeting during ECA Spring 2004 Engineering Summit April 19-22, 2004 Tampa, FL

Harvey Waltersdorf – Chairman  
Bill Upstone – Vice Chairman  
Bill Peverill – Secretary

**PRELIMINARY MEETING AGENDA-CE-2.1 SUBCOMMITTEE ON TEST PROCEDURES**

October 8-9, 2003, San Antonio, TX

1. Approval of the May 12-13, 2003 minutes

2. TEST PROCEDURE PROJECTS (BY PROJECT NUMBER)

SP-4829, TP-33A, Inductance 100nH-100mH, (Jeff Toran & Carl Fritz)

SP-4896, TP-62A, Terminal Strength, (Carl Fritz)\*\*

SP-4903, TP-56A, Resistance to Soldering Heat(Carl Fritz)

SP-4918, TP-58, Temp Life With Mechanical Loading (Bill Upstone & Carl Fritz)

PN-4942, TP-60, General Methods for Porosity Testing (John Healy)

PN-4945, TP-29, Contact Retention, (Bill Upstone & Rick Taylor)

PN-4963, TP-65, MFG (Max Peel)

3. TEST PROCEDURES AWAITING PROJECT NUMBERS (BY TP NUMBER)

TP-12, Restricted Entry, (Bill Upstone & Rick Taylor)\*\*

TP-15, Contact Strength, (Al Davis)\*\*

TP-17, Temperature Life(Max Peel & Vince Pascucci)

TP-18, Visual Inspection, (Frank Ruffino)\*\*

TP-31, Humidity, (Max Peel & Frank Ruffino)

TP-32C, Thermal Shock, (Max Peel & Frank Ruffino)

TP-41C, Cable Flexing, (Max Peel)

TP-48A, Metallic Coating Thickness, (Ed Mikoski)

TP-55, Current Cycling, (Max Peel)\*\*

TP-59, Low Temperature, (Frank Ruffino)\*\*

TP-75, Lightning Strike, (Al Davis)

TP-81, Combustability of Connector Housings(Max Peel)

TP-82, Corrosivity of Plastics(Max Peel)\*\*

\*\* Past due for 5 year review

4. STG Reports

STG-29-2.1 Performance Criteria(EIA-364-1000.01)-John Healy and Max Peel

STG-32-2.1 Electronic (Signal) Test Methods-Jeff Toran

5. Other Business

A. Proposed Cancellation Notice of MIL-STD-1344 dated Mar 27, 2003(Bill Peverill)

B. Proposed Thermal Cycling Procedure Draft 8/22/2001- (Max Peel)

C. Current Rating Verification Procedure EIA-364-1000.02 PN-3787 (Max Peel)

- B. Concerns on Test Sequences in TS-10000.01 (Max Peel)
- C. Qualification Procedure for Tin Whisker formation on Pb-Free Reflow Soldering.  
(Frank Ruffino)
- D. Qualification Procedure for Connector Heat Resistance to Pb-Free Reflow Soldering.  
(Frank Ruffino)

5. New Business

- A. Test Procedures for RF Products ( Harvey Waltersdorf)

Bill Peverill  
Chairman CE-2.1

08/21/03